



Power MOSFETS

DATASHEET

LM30120DAQ8A

Dual N-Channel
Enhancement Mode MOSFET

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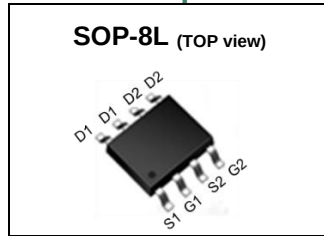


Quality Management Systems

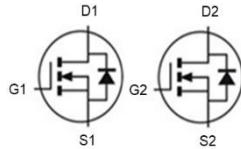
ISO 9001:2015 Certificate

Dual N-Channel Enhancement Mode MOSFET

Pin Description



Symbol



Product Summary

Symbol	Dual N-Channel	Unit
V_{DSS}	30	V
$R_{DS(ON)-Max}$	12	m Ω
ID	8	A

Feature

- Fast switching speed
- Reliable and Rugged
- ROHS Compliant & Halogen-Free
- 100% UIS Tested

Applications

- DC-DC Converters
- Portable equipment application

Ordering Information

Orderable Part Number	Package Type	Form	Shipping
LM30120DAQ8A	SOP-8L(Dual)	Tape & Reel	3000 / Tape & Reel

Absolute Maximum Ratings ($T_J=25^\circ\text{C}$ Unless Otherwise Noted)

Symbol	Parameter		Dual N-Channel	Unit
V_{DSS}	Drain-Source Voltage		30	V
V_{GSS}	Gate-Source Voltage		± 20	
T_J	Maximum Junction Temperature		150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range		-55 to 150	$^\circ\text{C}$
$I_{DM}^{(1)}$	Pulse Drain Current Tested	$T_A=25^\circ\text{C}$	20	A
I_D	Continuous Drain Current	$T_A=25^\circ\text{C}$	8	A
		$T_A=70^\circ\text{C}$	6.4	
P_D	Maximum Power Dissipation	$T_A=25^\circ\text{C}$	1.3	W
		$T_A=70^\circ\text{C}$	0.8	
$I_{AS}^{(2)}$	Avalanche Current, Single pulse	$L=0.1\text{mH}$	18	A
$E_{AS}^{(2)}$	Avalanche Energy, Single pulse	$L=0.1\text{mH}$	16	mJ

Thermal Characteristics

Symbol	Parameter		Rating	Unit
$R_{\theta JA}^{(3)}$	Thermal Resistance-Junction to Ambient	Steady State	100	$^\circ\text{C/W}$

Note ① : Max. current is limited by junction temperature.

Note ② : UIS tested and pulse width are limited by maximum junction temperature 150°C

Note ③ : Surface Mounted on 1in^2 FR-4 board with 1oz.

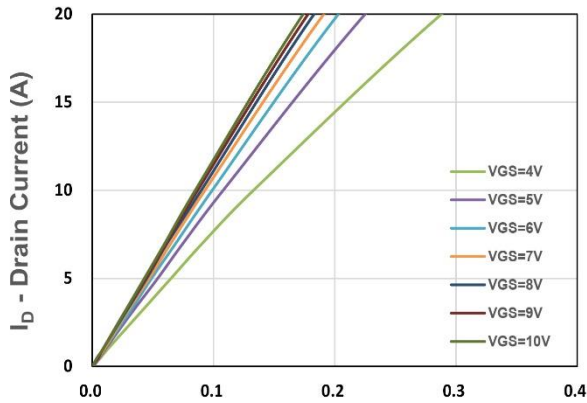
Dual N-Channel Electrical Characteristics (T_J=25°C Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Static Electrical Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =250uA	30	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =24V, V _{GS} =0V	-	-	1	uA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =250uA	1.1	1.6	2.1	V
I _{GSS}	Gate Leakage Current	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
R _{DS(ON)} ^④	Drain-Source On-state Resistance	V _{GS} =10V, I _{DS} =10A	-	10	12	mΩ
		V _{GS} =4.5V, I _{DS} =5A	-	12	16	
gfs	Forward Transconductance	V _{DS} =5V, I _{DS} =5A	-	2.5	-	S
Dynamic Characteristics ^⑥						
R _G	Gate Resistance	V _{GS} =0V,V _{DS} =0V, Freq.=1MHz	-	3.2	-	Ω
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =15V, Freq.=1MHz	-	873	-	pF
C _{oss}	Output Capacitance		-	113	-	
C _{rss}	Reverse Transfer Capacitance		-	105	-	
td(ON)	Turn-on Delay Time	V _{GS} =10V,V _{DS} =15V, I _D =1A,R _{GEN} =6Ω	-	18	-	nS
t _r	Turn-on Rise Time		-	31	-	
t _{d(OFF)}	Turn-off Delay Time		-	31	-	
t _f	Turn-off Fall Time		-	17	-	
Q _g	Total Gate Charge	V _{GS} =4.5V,V _{DS} =15V I _D =10A	-	10.3	-	nC
Q _g	Total Gate Charge	V _{GS} =10V,V _{DS} =15V, I _D =10A	-	20.6	-	
Q _{gs}	Gate-Source Charge		-	2.33	-	
Q _{gd}	Gate-Drain Charge		-	4.9	-	
Source-Drain Characteristics						
V _{SD} ^④	Diode Forward Voltage	I _{SD} =1A, V _{GS} =0V	-	0.7	1.1	V
t _{rr}	Reverse Recovery Time	I _F =1A, V _R =20V	-	25.5	-	nS
Q _{rr}	Reverse Recovery Charge	dI _F /dt=100A/μs	-	10.8	-	nC

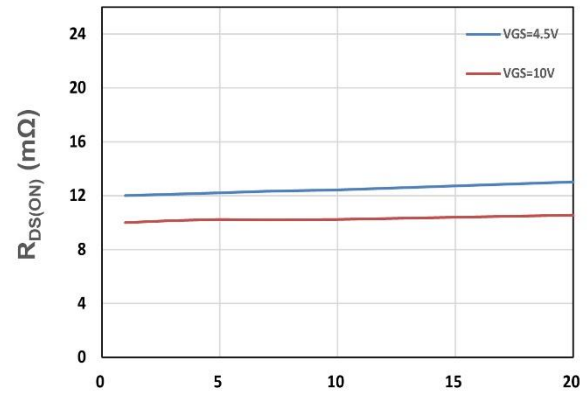
Note ④ : Pulse test (pulse width≤300us, duty cycle≤2%).

Note ⑤ : Guaranteed by design, not subject to production testing.

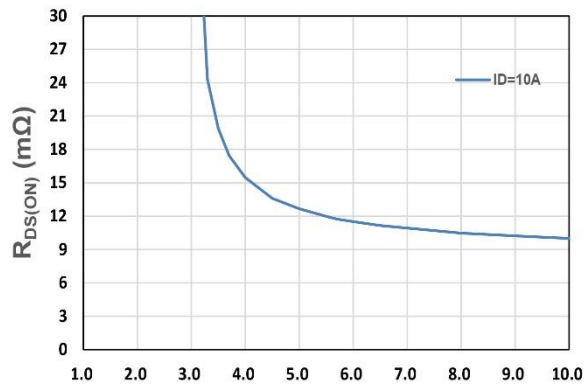
Dual N-Channel Typical Characteristics



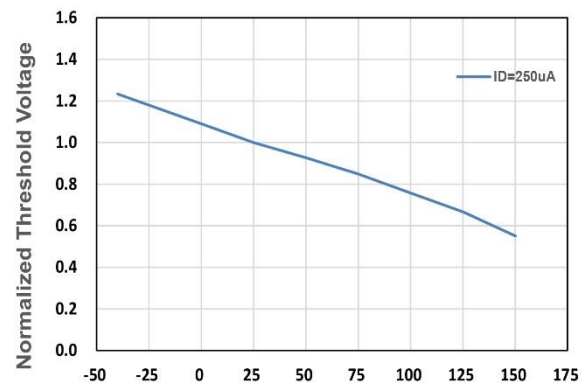
V_{DS} - Drain - Source Voltage (V)
Figure 1. Output Characteristics



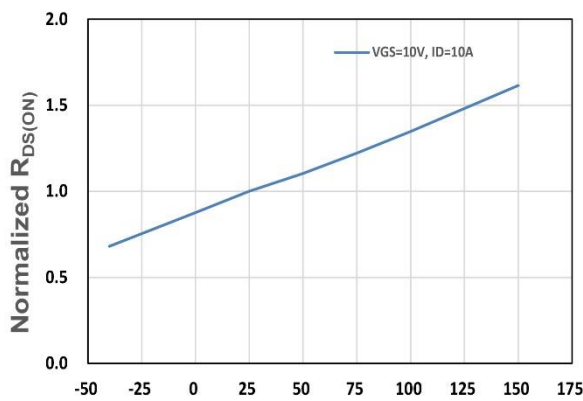
I_D - Drain Current (A)
Figure 2. On-Resistance vs. I_D



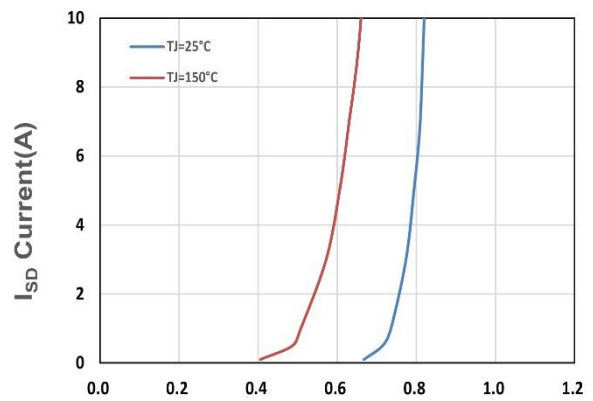
V_{GS} - Gate - Source Voltage (V)
Figure 3. On-Resistance vs. V_{GS}



T_j , Junction Temperature($^{\circ}C$)
Figure 4. Gate Threshold Voltage



T_j , Junction Temperature($^{\circ}C$)
Figure 5. Drain-Source On Resistance



V_{SD} , Source-Drain Voltage(V)
Figure 6. Source-Drain Diode Forward

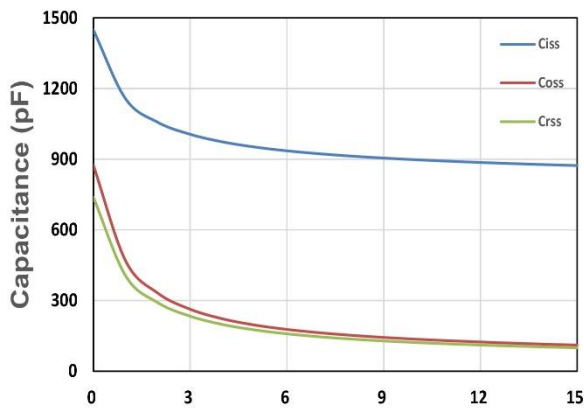


Figure 7. Capacitance

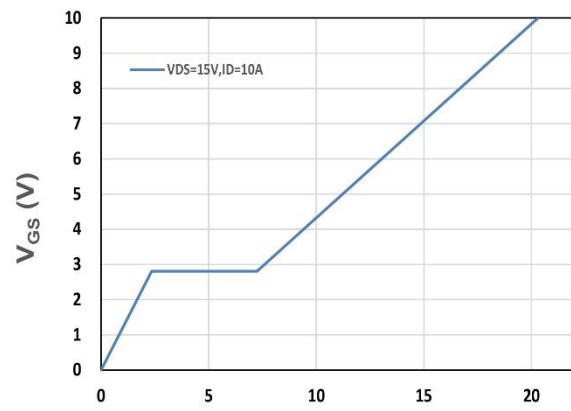


Figure 8. Gate Charge Characteristics

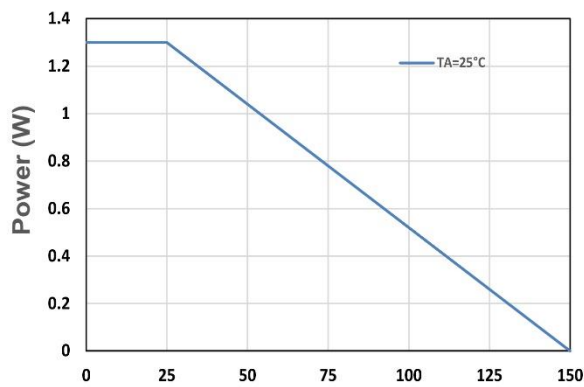


Figure 9. Power Dissipation

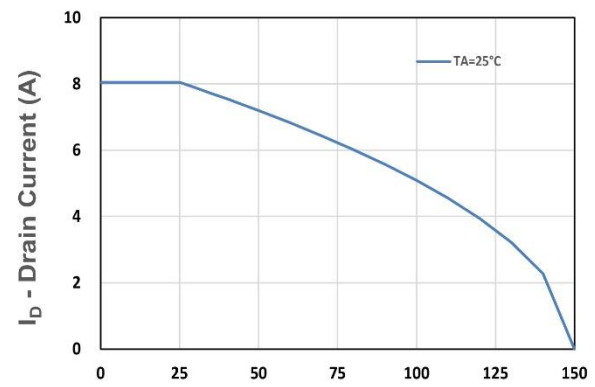


Figure 10. Drain Current

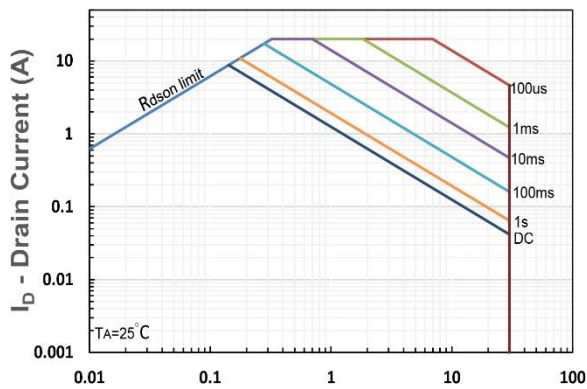


Figure 11. Safe Operating Area

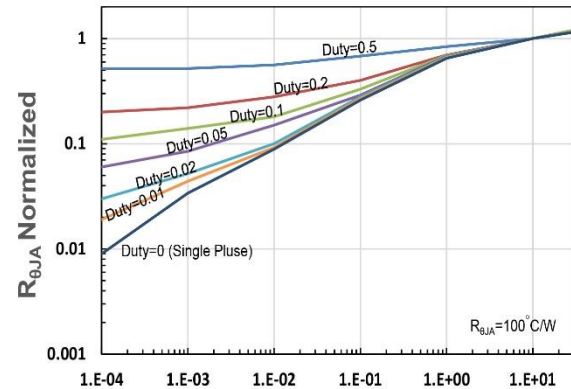


Figure 12. $R_{\theta JA}$ Transient Thermal Impedance